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YANG et al.(10) **Pub. No.: US 2022/0377940 A1**(43) **Pub. Date: Nov. 24, 2022**(54) **LIQUID COOLED PLATE AND
ELECTRONIC COMPUTING DEVICE****Publication Classification**(71) Applicant: **SHENZHEN ENVICOOL
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(57) **ABSTRACT**

A liquid cooled plate and an electronic computing device are provided. The liquid cooled plate includes multiple channels communicated in sequence, and adjacent channels are communicated via a communicating portion. Multiple partitions divide each of the channels to multiple flow passages, and a part of each of the partitions extends into the communicating portion, and lengths of the multiple partitions extending into the communicating portion gradually increases or decreases according to a preset rule. With this arrangement, the coolant can be collected and redistributed before entering the next channel, which is more conducive to the uniform distribution of the coolant, thereby improving the overall heat exchange capacity of the liquid cooled plate, and thus can better meet the actual usage requirements.

